ABSTRACT

An adhesive composition containing an epoxy resin (A), an epoxy resin curing agent (B), a phenoxy resin (C), and an inorganic filler (D), in which the phenoxy resin (C) has an elastic modulus of 500 MPa or more at 25°C, a proportion of the phenoxy resin (C) in a total content of the epoxy resin (A) and the phenoxy resin (C) is 10 to 60 mass%, a nanoindentation hardness at 25°C of a film-like adhesive before curing formed using the adhesive composition is 0.10 MPa or more, and the Young's modulus at 25°C of a film-like adhesive before curing formed using the adhesive composition is 100 MPa or more;

a film-like adhesive using the adhesive composition; and

a semiconductor package using the film-like adhesive and a producing method thereof.

(Fig.1)